



Product Change Notification

Change Notification #: 117258 - 00
Change Title: Intel® Server Chassis FC2HAC16W3,
Intel® Server Chassis FC2HLC21W3,
PCN 117258-00, Product Design,
Power Distribution Board
Date of Publication: November 19, 2019

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:*	November 30, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is replacing an IC that is an isolation buffer included in the OPB Power Distribution Board. The previous IC works between $4.5V < VCC < 5.5V$ but the PDB design circuit works $3.3V < VCC$. To prevent any issue Intel is matching the voltages of IC VR with PDV design.

The new PDB design impacts the products described in the table "Products Affected".

Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
FC2HLC21W3	999D3Z	K25121-005	K25121-006
FC2HAC16W3	999D40	K25122-005	K25122-006

PCN Revision History:

Date of Revision:

November 19, 2019

Revision Number:

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Reason:

Originally Published PCN



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The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asm0.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

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